

DATA SHEET

SKY65152-11: 2.4-2.5 GHz WLAN Power Amplifier

Applications

- IEEE 802.11 b/g WLANs
- ISM band transmitters
- WCS fixed wireless
- Wireless access nodes

Features

- EVM < 2.5% for $P_{OUT} > +27$ dBm
- High gain = 32 dB
- Internal RF match with DC block and active bias circuits
- Internal on/off control circuit
- Internal, high dynamic range power detector
- Single DC supply = +5 V
- Operating temperature = -40°C to $+85^{\circ}\text{C}$
- Small, MCM (20-pin, 6 x 6 mm) package (MSL3, 260 $^{\circ}\text{C}$ per JEDEC J-STD-020)

NEW

Skyworks offers lead (Pb)-free RoHS (Restriction of Hazardous Substances) compliant packaging.

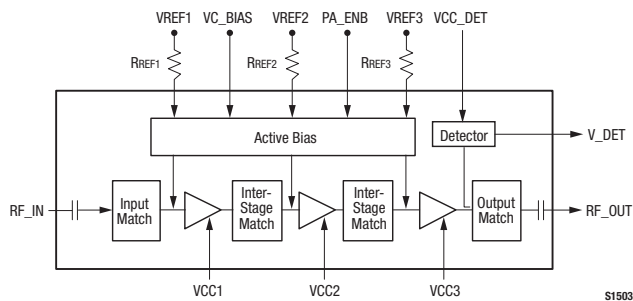


Figure 1. SKY65152-11 Block Diagram

Description

The SKY65152-11 is a Microwave Monolithic Integrated Circuit (MMIC) Power Amplifier (PA) with superior output power, linearity, and efficiency. These features make the SKY65152-11 ideal for Wireless Local Area Network (WLAN) applications. The high linearity (low EVM) and high efficiency of this device makes it ideal for use in the transmit chain of WLAN access points or modems.

The SKY65152-11 is fabricated using Skyworks high reliability Heterojunction Bipolar Transistor (HBT) InGaP process, which allows for single supply operation while maintaining high efficiency and good linearity. The device is internally matched and mounted in a 20-pin, 6 x 6 mm Multi-Chip Module (MCM) Surface-Mounted Technology (SMT) package, which allows for a highly manufacturable low cost solution.

A functional block diagram is shown in Figure 1. The pin configuration and package are shown in Figure 2. Signal pin assignments and functional pin descriptions are provided in Table 1.

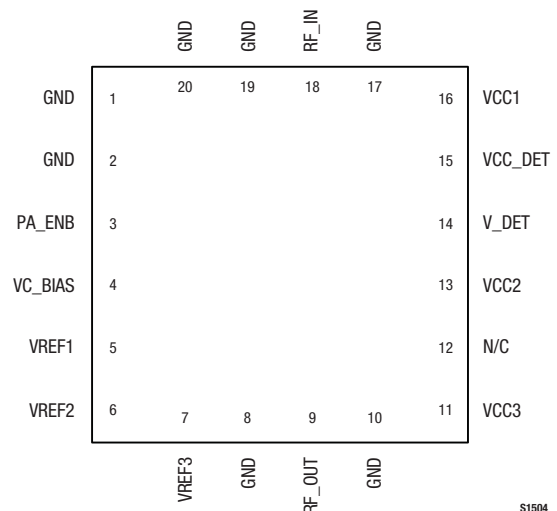


Figure 2. SKY65152-11 Pinout – 20-Pin MCM (Top View)

Table 1. SKY65152-11 Signal Descriptions

Pin #	Name	Description	Pin #	Name	Description
1	GND	Ground	11	VCC3	Stage 3 collector voltage
2	GND	Ground	12	N/C	No connection
3	PA_ENB	PA on/off control signal (on = +3 V to VCC; off = 0 to 0.5 V)	13	VCC2	Stage 2 collector voltage
4	VC_BIAS	Bias voltage	14	V_DET	Detector output signal
5	VREF1	Bias reference voltage 1	15	VCC_DET	Detector supply voltage
6	VREF2	Bias reference voltage 2	16	VCC1	Stage 1 collector voltage
7	VREF3	Bias reference voltage 3	17	GND	Ground
8	GND	Ground	18	RF_IN	RF input
9	RF_OUT	RF output	19	GND	Ground
10	GND	Ground	20	GND	Ground

Note: The center attachment pad must have a low inductance and low thermal resistance connection to the printed circuit board ground plane.

Functional Description

The SKY65152-11 is a three-stage, HBT InGaP device optimized for high linearity and power efficiency. It contains all of the needed RF matching and DC biasing circuits. An in-module active bias circuit is included within the device for all three amplifier stages, which provides excellent gain tracking over temperature and voltage variations.

The first, second, and output stages are independently supplied using the VCC1, VCC2, and VCC3 signals (pins 16, 13 and 11, respectively). The DC control voltage that sets the bias for all three stages is supplied by the VC_BIAS signal (pin 4). The Evaluation Board includes shunt decoupling capacitors on these pins to suppress any possible bias affect on the RF signal at low frequencies.

The bias reference voltages for stages 1, 2, and 3 are supplied using the common lines VREF1, VREF2, and VREF3 (pins 5, 6, and 7, respectively). The maximum voltage for these pins is 4 V. Resistors R1, R2, and R3 on the Evaluation Board set the correct bias to these pins when attached to a 5 V power supply.

The SKY65152-11 includes an internal PA enable control pin (pin 3) for fast RF on/off control. Zero volts turns off the PA while 3 to 5 V enables the PA. The device also provides an output power detector voltage, V_DET, at pin 14. A bias voltage is required to operate the detector. The detector supply voltage is provided

through the VCC_DET signal (pin 15). The maximum voltage for this pin is 4 V. Resistor R5 on the Evaluation Board sets the correct bias to this pin when attached to a 5 V power supply.

Pin 18 is the RF input and Pin 9 is the RF output. External DC blocking or RF matching is not required on the RF input and output. Grounding is through several ground pins and the package center ground.

These features make the device suitable for wideband digital applications where PA linearity and power consumption are of critical importance (e.g., WLANs). The device has been characterized with the highest specified data rates for 802.11b (11 Mbps) and 802.11g (54 Mbps). Under these stringent test conditions, the device exhibits excellent spectral purity and power efficiency.

Electrical and Mechanical Specifications

The absolute maximum ratings of the SKY65152-11 are provided in Table 2. The recommended operating conditions are specified in Table 3 and electrical specifications are provided in Table 4.

Performance characteristics for the SKY65152-11 are illustrated in Figures 3 through 14.

Table 2. SKY65152-11 Absolute Maximum Ratings (Note 1)

Parameter	Symbol	Minimum	Maximum	Units
RF output power	P _{OUT}		+30	dBm
Supply voltage (V _{CC} , V _{C_BIAS} , and PA_ENB) (Note 2)	V _{CC}	4.5	5.5	V
Total supply current	I _{CC}		850	mA
Reference voltage (Note 2)	V _{REF}		4	V
Detector supply voltage (V _{CC_DET}) (Note 2)			4	V
Power dissipation	P _D		3.3	W
Case temperature	T _C	−40	+85	°C
Storage temperature	T _{STG}	−55	+125	°C
Junction temperature	T _J		+150	°C
Thermal resistance	Θ _{JC}		20	°C/W

Note 1: Exposure to maximum rating conditions for extended periods may reduce device reliability. There is no damage to device with only one parameter set at the limit and all other parameters set at or below their nominal value. Exceeding any of the limits listed here may result in permanent damage to the device.

Note 2: Voltage levels measured at the pins of the package. The Evaluation Board supply voltage levels may be different. Refer to the Evaluation Board schematic diagram in this document.

CAUTION: Although this device is designed to be as robust as possible, Electrostatic Discharge (ESD) can damage this device. This device must be protected at all times from ESD. Static charges may easily produce potentials of several kilovolts on the human body or equipment, which can discharge without detection. Industry-standard ESD precautions should be used at all times.

Table 3. SKY65152-11 Recommended Operating Conditions

Parameter	Symbol	Minimum	Typical	Maximum	Units
RF output power	P _{OUT}		+27		dBm
Supply voltage (Note 1)	V _{CC} , V _{C_BIAS}		5		V
Reference voltage (Note 1)	V _{REF}		2.5		V
Detector supply voltage (Note 1)	V _{CC_DET}		3.6		V
Operating frequency	f	2412		2462	MHz
Case temperature	T _C	−40	+25	+85	°C

Note 1: Voltage levels measured at the pins of the package. The Evaluation Board supply voltage levels may be different. Refer to the Evaluation Board schematic diagram in this document.

Table 4. SKY65152-11 Electrical Specifications (Note 1)

(VCC1 = VCC2 = VCC3 = VREF1 = VREF2 = VREF3 = VC_BIAS = VCC_DET = PA_ENB = 5 V, Characteristic Impedance [Z₀] = 50 Ω, T_c = 25 °C, Frequency = 2.442 GHz, Unless Otherwise Noted)

Parameter	Symbol	Test Condition	Min	Typical	Max	Units
IEEE 802.11g Orthogonal Frequency Division Multiplexing Input Signal, Data Rate = 54 Mbps						
Error Vector Magnitude	EVM	P _{OUT} = +27 dBm		2	2.5	%
Continuous Wave Input Signal						
Small signal gain	G	P _{IN} = -25 dBm	30	32		dB
Gain flatness over band	P _{OUT}	2.4 GHz to 2.5 GHz		1.0	1.4	dB
Gain flatness over channel	P _{OUT_EVM}	Over any 16.25 MHz within band		±0.10	±0.15	dB
Input return loss	S ₁₁			-12	-10	dB
2 nd harmonics	2f ₀	CW input		-16.5	-14.0	dBm
Detector voltage	V _{DET}	P _{OUT} = +27 dBm	0.79	0.83	0.87	V
Operational current	I _{CC}	Peak P _{OUT} = +27 dBm		790	830	mA
Output power @ 1 dB compression	P _{1dB}		+32	+33		dBm
Quiescent current	I _{CCQ}	No RF		490	510	mA
Noise Figure	NF			5	6.5	dB
Power Up/Down Control						
Power up	PA_ENB on		3	5		V
Power down	PA_ENB off			0	0.5	V
Standby current	ISB	PA_ENB = 0 V		3	5	μA

Note 1: Performance is guaranteed only under the conditions listed in this Table and is not guaranteed over the full operating or storage temperature ranges. Operation at elevated temperatures may reduce reliability of the device.

Typical Performance Characteristics

($V_{CC1} = V_{CC2} = V_{CC3} = V_{REF1} = V_{REF2} = V_{REF3} = V_{C_BIAS} = V_{C_DET} = PA_ENB = 5\text{ V}$, CW, Characteristic Impedance [Z_0] = $50\ \Omega$, $T_c = 25\ ^\circ\text{C}$, Frequency = 2.442 GHz, Unless Otherwise Noted)

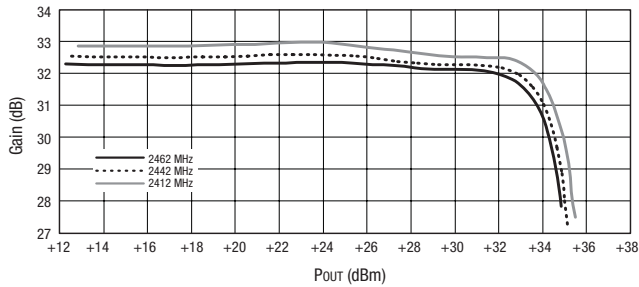


Figure 3. Gain vs Output Power Over Frequency

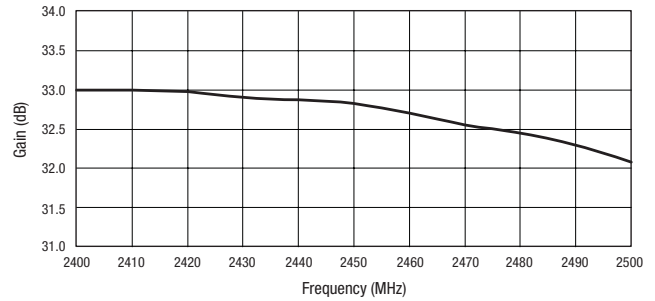


Figure 4. Small Signal Gain vs Frequency

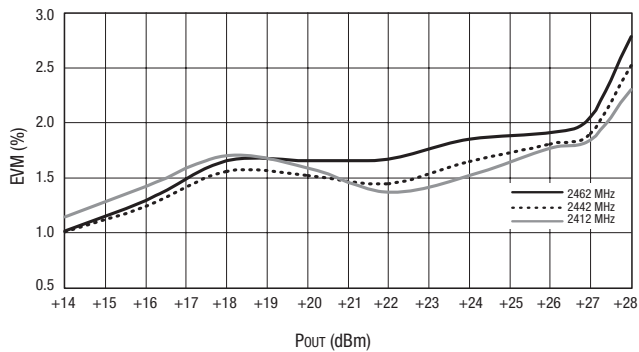


Figure 5. EVM vs Output Power Over Frequency
(802.11g, OFDM, 64 QAM @ 54 Mbps)

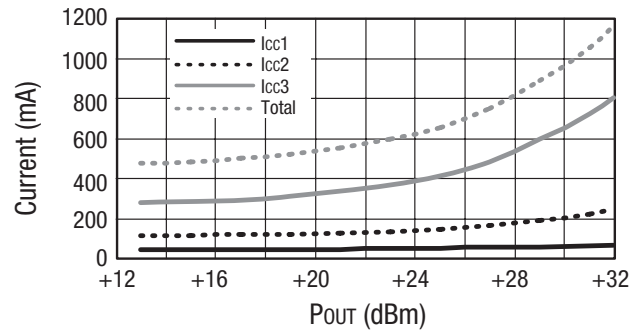


Figure 6. Current vs Output Power

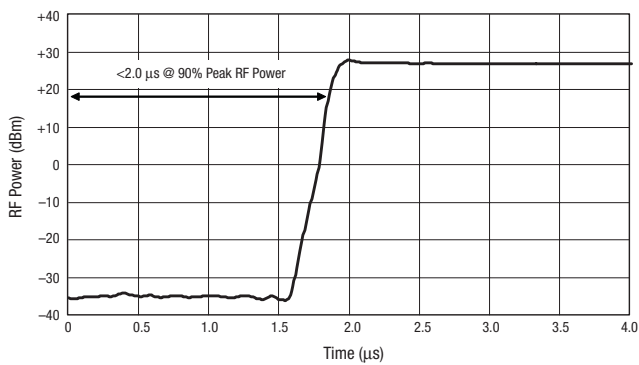


Figure 7. Output Power vs Enable Time

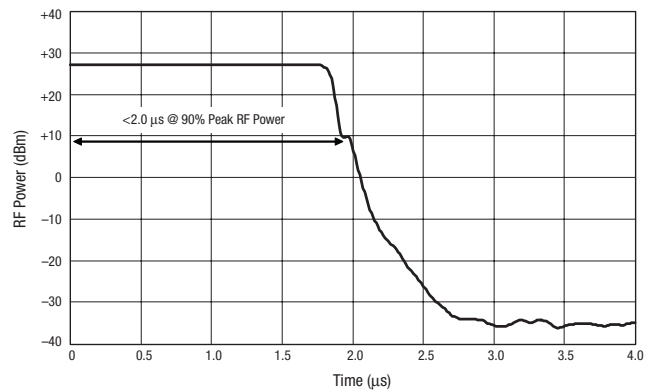


Figure 8. Output Power vs Disable Time

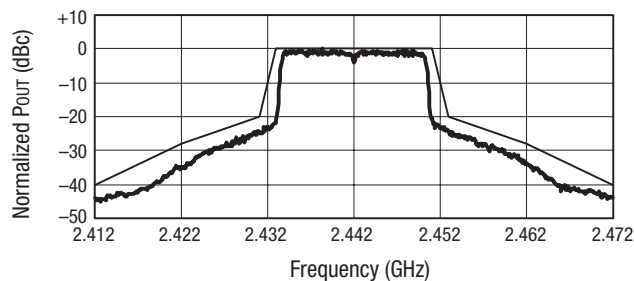


Figure 9. Spectral Response @ $P_{out} = +30$ dBm (802.11g, OFDM, 64 QAM @ 54 Mbps)

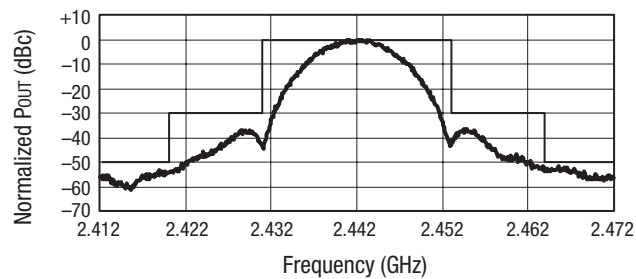


Figure 10. Spectral Response @ $P_{out} = +31$ dBm (802.11b, CCK @ 11 Mbps)

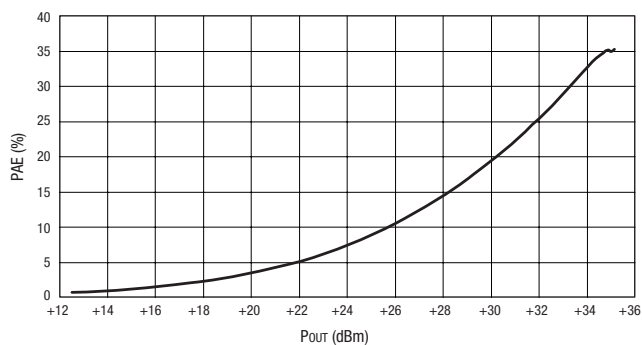


Figure 11. PAE vs Output Power

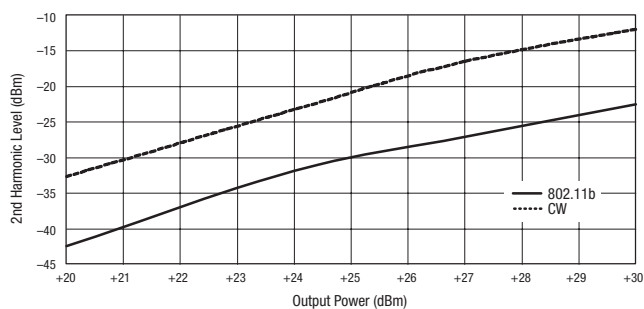


Figure 12. Second Harmonic vs Output Power

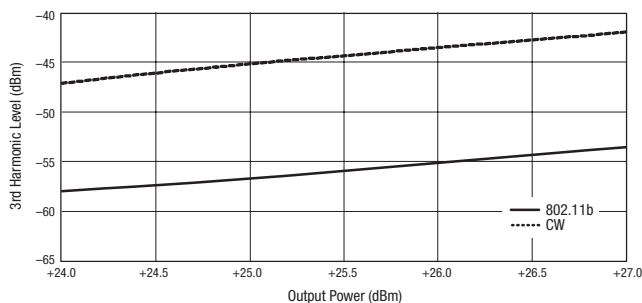


Figure 13. Third Harmonic vs Output Power

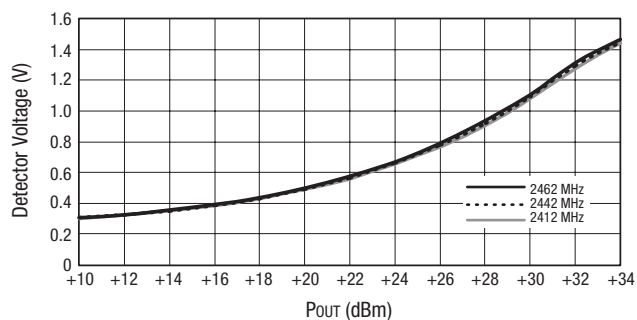


Figure 14. Detector Voltage vs Output Power

Evaluation Board Description

The SKY65152-11 Evaluation Board is used to test the performance of the SKY65152-11 PA. An Evaluation Board schematic diagram is provided in Figure 15. An assembly drawing for the Evaluation Board is shown in Figure 16.

An Evaluation Board layer detail drawing is shown in Figure 17. Layer detail physical characteristics are noted in Figure 18. Table 5 provides the Bill of Materials (BOM) list for Evaluation Board components.

Circuit Design Considerations

The following design considerations are general in nature and must be followed regardless of final use or configuration:

1. Paths to ground should be made as short as possible.
2. The ground pad of the SKY65152-11 has special electrical and thermal grounding requirements. This pad is the main thermal conduit for heat dissipation. Since the circuit board acts as the heat sink, it must shunt as much heat as possible from the device. Therefore, design the connection to the ground pad to dissipate the maximum wattage produced by the circuit board. Multiple vias to the grounding layer are required.
3. Bypass capacitors should be used on the DC supply lines. An RF inductor is required on the VCC supply line to block RF signals from the DC supply. Refer to the schematic drawing in Figure 15 for further details.
4. The RF lines should be well separated from each other with solid ground in between traces to maximize input-to-output isolation.

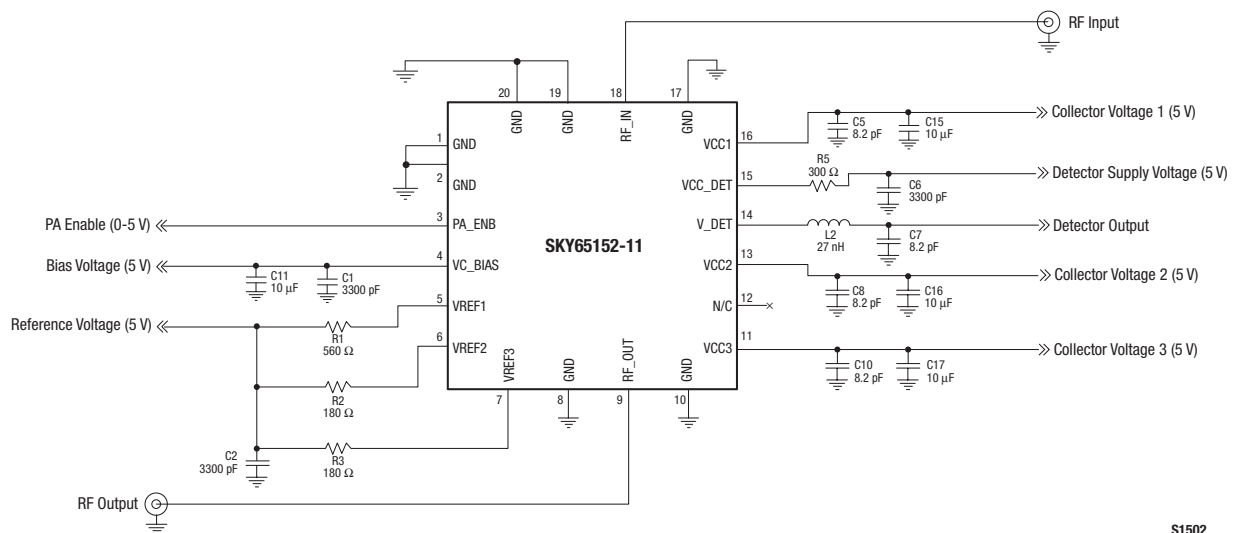
NOTE: A poor connection between the slug and ground increases junction temperature (T_J), which reduces the lifetime of the device.

Evaluation Board Test Procedure

- Step 1: Connect a +5 V supply to the VCC1, VCC2, VCC3, VREF1, VREF2, VREF3, VC_BIAS, VCC_DET, and PA_ENB pins. If available, enable the current limiting function of the power supply to 1000 mA.
- Step 2: If desired, connect a voltage meter to the V_DET pin.
- Step 3: Connect a signal generator to the RF signal input port. Set it to the desired RF frequency at a power level of -15 dBm or less to the Evaluation Board. **DO NOT** enable the RF signal.
- Step 4: Connect a spectrum analyzer to the RF signal output port.
- Step 5: Enable the power supply.
- Step 6: Enable the RF signal.
- Step 7: Take measurements.

CAUTION: If the input signal exceeds the rated power, the SKY65152-11 Evaluation Board can be permanently damaged.

NOTE: It is important to adjust the VCC voltage source so that +5 V is measured at the board. The high collector currents will drop the collector voltage significantly if long leads are used. Adjust the bias voltage to compensate.



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Figure 15. SKY65152-11 Evaluation Board Schematic

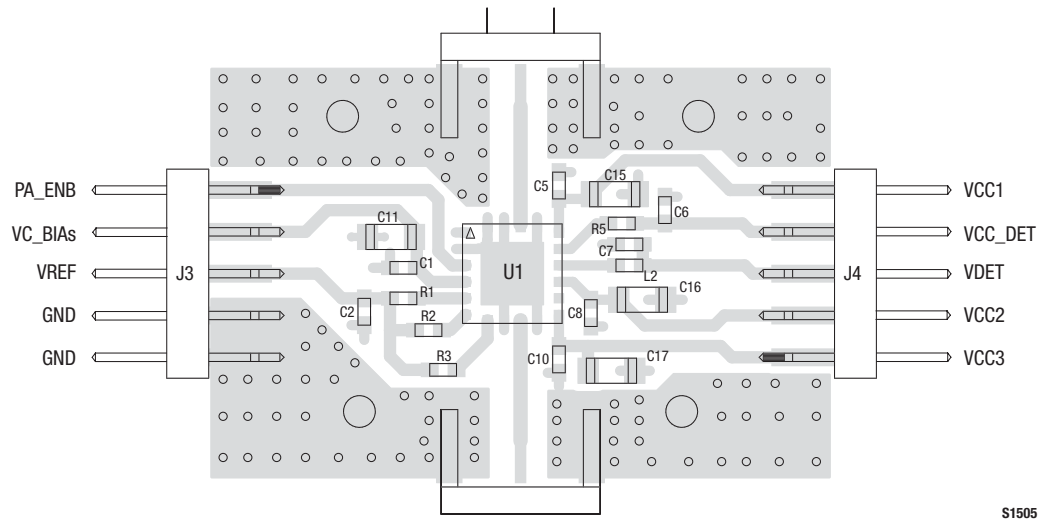
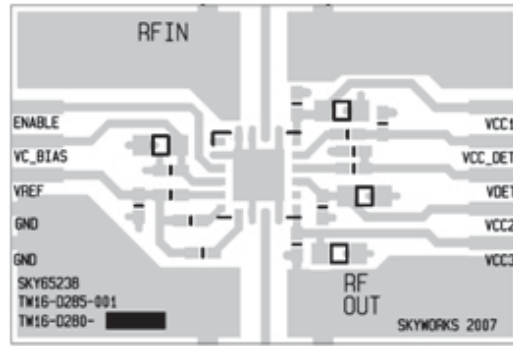
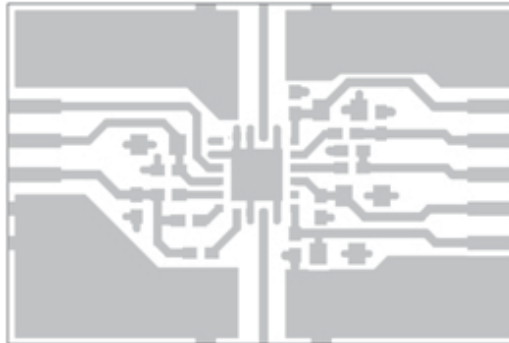


Figure 16. SKY65152-11 Evaluation Board Assembly Diagram

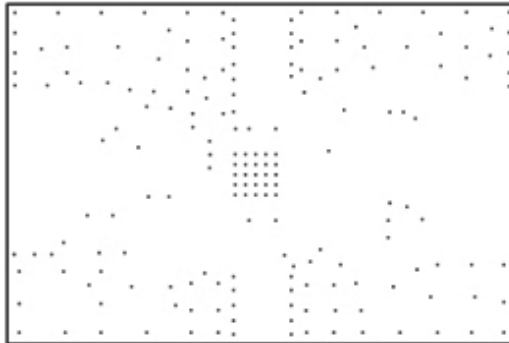
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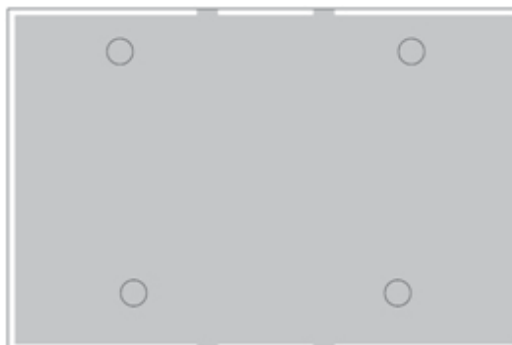
Layer 1: Silk Screen



Layer 1: Top Metal



Layer 2 and 3: Ground



Layer 4: Backside Ground

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Figure 17. SKY65152-11 Evaluation Board Layer Detail

Cross Section	Name	Thickness (mils)	Material	ϵ_r
	L1	1.4	Cu	—
	Lam1	12	Rogers 4003-12	3.38
	L2 GND	1.4	Cu, 1 oz.	—
	Lam2	4	FR4-4	4.35
	L3 GND	1.4	Cu, 1 oz.	—
	Lam3	12	FR4-12	4.35
	L4	1.4	Cu, 1 oz.	—

Figure 18. Evaluation Board Layer Detail Physical Characteristics**Table 5. SKY65152-11 Evaluation Board Bill of Materials**

Component	Value	Size	Product #	Manufacturer	Manufacturer's Part #	Characteristics
C1, C2, C6	3300 pF	0603	5404R28-015	Murata	GRM188R71H332KD01J	X7R, 50 V, $\pm 10\%$
C5, C7, C8, C10	8.2 pF	0603	5404R98-010	Murata	GRM1885C1H8R2CZ01D	C0G, 50 V, ± 0.25 pF
C11, C15, C16, C17	10 μ F	0603	5404R91-005	TDK	C3216X5R0J106KT	X5R, 6 V, $\pm 10\%$
L2	27 nH	0603	5332R34-030	Taiyo-Yuden	HK160827NJ-T	$\pm 5\%$, SRF 2200 MHz
R1	560 Ω	0603	5424R20-045	Rohm	MCR03EZHUJ680	50 V, 0.063 W, $\pm 5\%$
R2, R3	180 Ω	0603	5424R20-031	Rohm	MCR03EZHUJ180	50 V, 0.063 W, $\pm 5\%$
R5	300 Ω	0603	5424R20-036	Rohm	MCR03EZHUJ300	50 V, 0.063 W, $\pm 5\%$

Application Circuit Notes

Center Ground. It is extremely important to sufficiently ground the bottom ground pad of the device for both thermal and stability reasons. Multiple small vias are acceptable and will work well under the device if solder migration is an issue.

GND (pins 1, 2, 8, 10, 17, 19, and 20). Attach all ground pins to the RF ground plane with the largest diameter and lowest inductance via that the layout allows. Multiple small vias are acceptable and will work well under the device if solder migration is an issue.

PA_ENB (pin 3). Internal PA enable control pin for fast on/off control (on = +3 V to VCC; off = 0 to 0.5 V).

VC_BIAS (pin 4). The bias supply voltage for stages 1 and 2, typically set to +5 V.

VREF1 (pin 5). Bias reference voltage for amplifier stage 1. This signal should be operated over the same voltage range as VCC with a nominal voltage of +5 V.

VREF2 (pin 6). Bias reference voltage for amplifier stage 2. This signal should be operated over the same voltage range as VCC with a nominal voltage of +5 V.

VREF3 (pin 7). Bias reference voltage for amplifier stage 3. This signal should be operated over the same voltage range as VCC with a nominal voltage of +5 V.

RF_OUT (pin 9). Amplifier RF output pin ($Z_0 = 50 \Omega$). The module includes an onboard internal DC blocking capacitor. All impedance matching is provided internal to the module.

VCC3 (pin 11). Supply voltage for the output (final) stage collector bias (typically +5 V). To bypass VCC3, capacitors C10 and C17 (see Figure 15) should be placed in the approximate location shown on the Evaluation Board, although exact placement is not critical.

N/C (pin 12). This pin is open and may or may not be connected to ground.

VCC2 (pin 13). Supply voltage for the second stage collector bias (typically +5 V). To bypass VCC2, capacitors C8 and C16 (see Figure 15) should be placed in the approximate location shown on the Evaluation Board, although exact placement is not critical.

V_DET (pin 14). The output power detector voltage signal. The detector load and settling time constant are set external to the device. Inductor L2 and capacitor C7 (see Figure 15) are set to yield a settling time of $< 0.5 \mu$ s.

VCC_DET (pin 15). The power detector supply voltage signal. Resistor R5 and capacitor C5 (see Figure 15) are used for proper bias and bypassing of this pin. VCC_DET (pin 15) may be connected to the PA_ENB supply (pin 3). The benefit of this is that the current draw consumed by the detector will not be wasted with the device in the off state.

VCC1 (pin 16). Supply voltage for the first stage collector bias (typically +5 V). To bypass VCC1, capacitors C5 and C15 (see Figure 15) should be placed in the approximate location shown on the Evaluation Board, although exact placement is not critical.

RF_IN (pin 18). Amplifier RF input pin ($Z_0 = 50 \Omega$). The module includes an onboard internal DC blocking capacitor. All impedance matching is provided internal to the module.

Package Dimensions

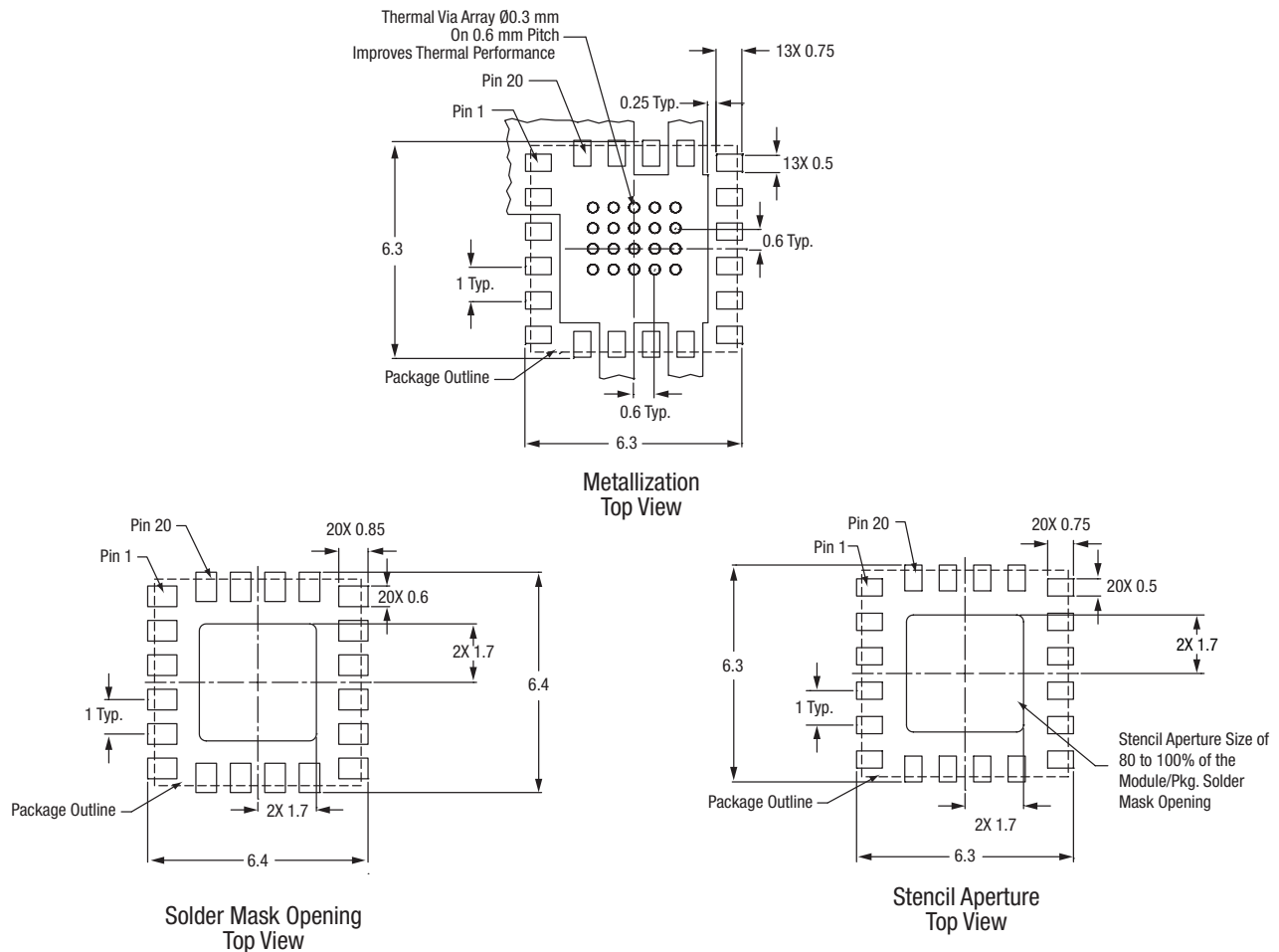
The PCB layout footprint for the SKY65152-11 is shown in Figure 19. Typical case markings are shown in Figure 20. Package dimensions for the 20-pin MCM are shown in Figure 21, and tape and reel dimensions are provided in Figure 22.

Package and Handling Information

Since the device package is sensitive to moisture absorption, it is baked and vacuum packed before shipping. Instructions on the shipping container label regarding exposure to moisture after the container seal is broken must be followed. Otherwise, problems related to moisture absorption may occur when the part is subjected to high temperature during solder assembly.

THE SKY65152-11 is rated to Moisture Sensitivity Level 3 (MSL3) at 260 °C. It can be used for lead or lead-free soldering.

Care must be taken when attaching this product, whether it is done manually or in a production solder reflow environment. Production quantities of this product are shipped in a standard tape and reel format. For packaging details, refer to the Skyworks Application Note, *Tape and Reel Information – RF Modules*, document number 101568.



All dimensions are in millimeters

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Figure 19. SKY65152-11 PCB Layout Footprint

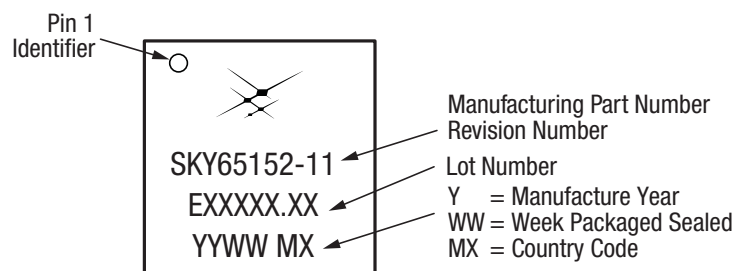


Figure 20. SKY65152-11 Typical Case Markings

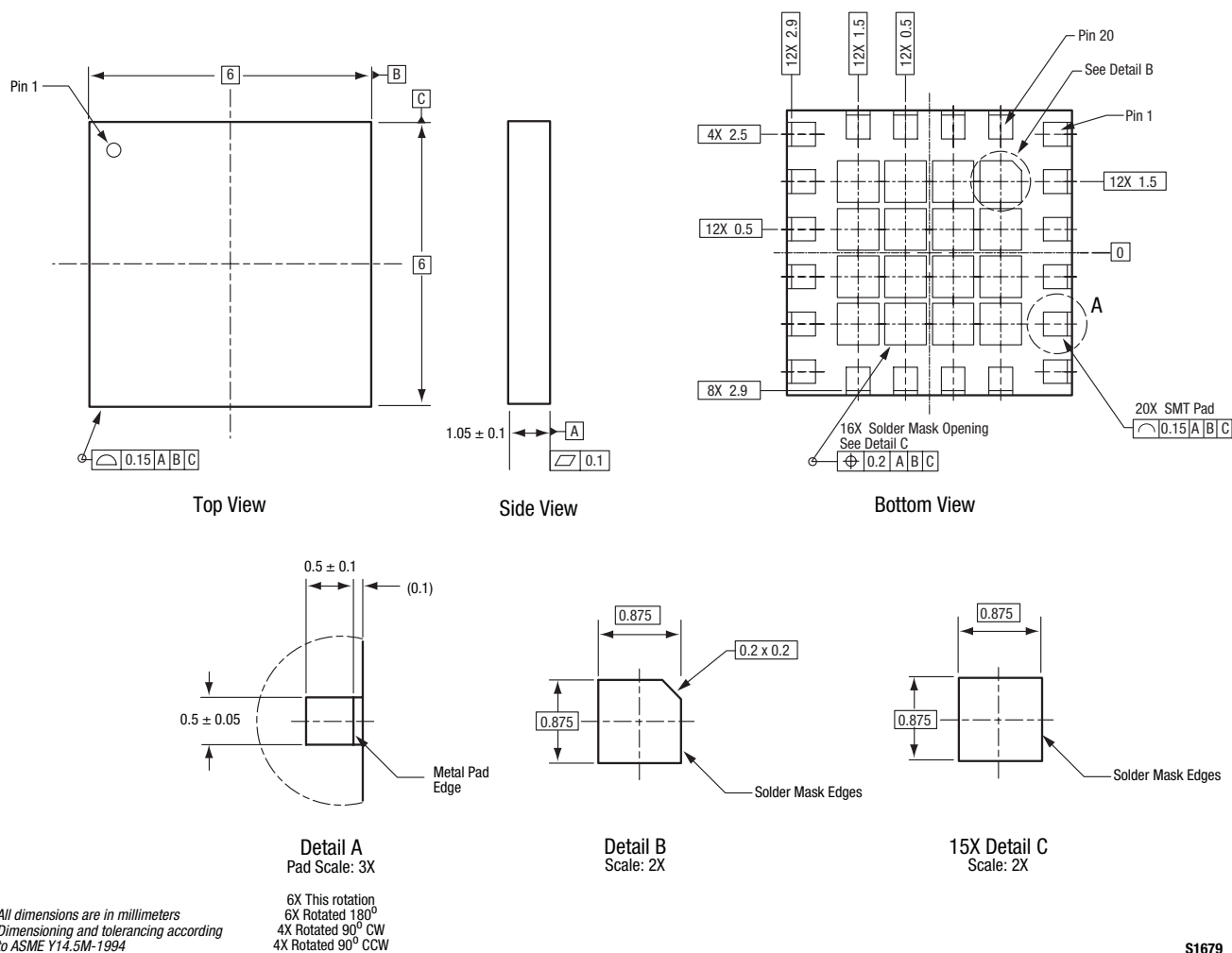
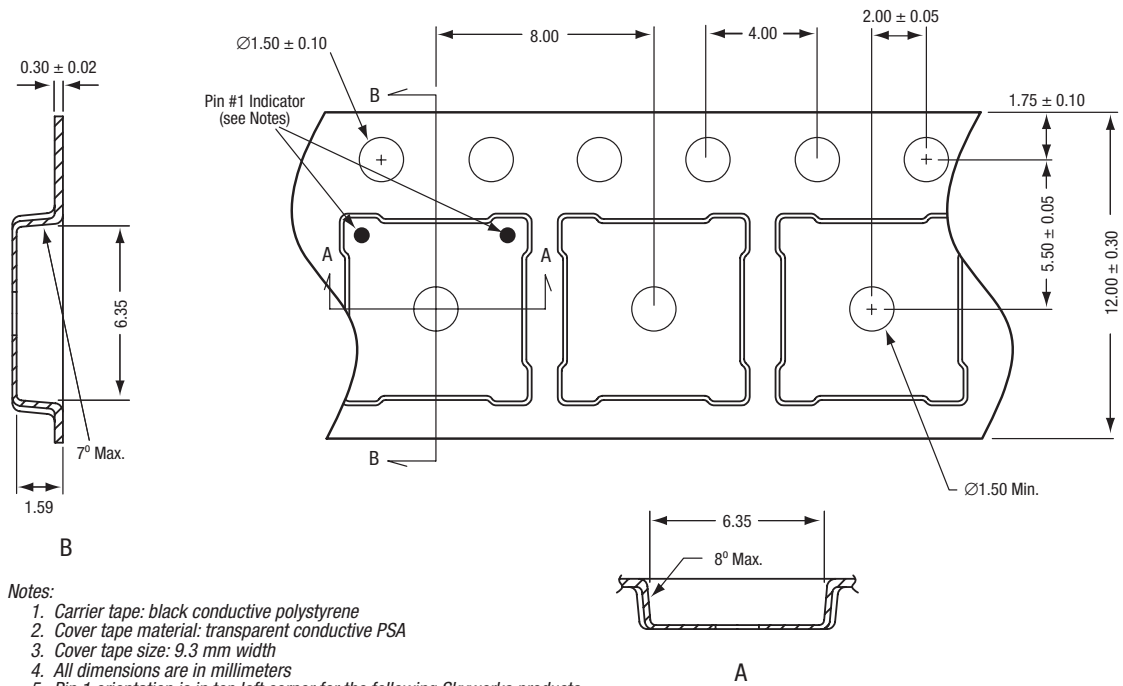


Figure 21. SKY65152-11 20-Pin MCM Package Dimensions

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S1183

Figure 22. SKY65152-11 20-Pin MCM Tape and Reel Dimensions

Ordering Information

Model Name	Manufacturing Part Number	Evaluation Kit Part Number
SKY65152-11 WLAN Power Amplifier	SKY65152-11 (Pb-free package)	TW16-D280-031

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